



Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134. Tel: (408) 943-2600

PRODUCT CHANGE NOTIFICATION

PCN: PCN171503

Date: April 11, 2017

Subject: Qualification of ChipMOS as an Additional Assembly Site for Select 54-Lead TSOPII Stacked Die Products.

To: GENERAL INBOX
ELEMENT14
ProductChangeNotices@element14.com

Description of Change:

Cypress announces the qualification of ChipMOS Technologies Inc. as an additional assembly site for select 54-Lead TSOPII (400mils) Pb-Free package stacked die products per the attached affected part list.

The 54-Lead TSOPII (400mils) Pb-Free stacked die package will be assembled at ChipMOS Technologies Inc. using the following set of materials:

Material	ChipMOS Set of Material	ASE-KH Taiwan Set of Material
Mold Compound	Hitachi 9200HF-U	Sumitomo EME-G631SH
Lead Finish	Matte Tin	Matte Tin
Die Attach Epoxy	Nitto EM710	Hitachi FH900
Bond Wire	0.8 mil Gold	0.8 mil Cu / 1.0 mil Gold

Benefit of Change:

Qualification of alternate manufacturing sites is part of the ongoing flexible manufacturing initiative announced by Cypress. The goal of the flexible manufacturing initiative is to provide the means for Cypress to continue to meet delivery commitments through dynamic, changing market conditions.

Part Numbers Affected: 8

Affected Parts: See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PCN will include all changes outlined in this PCN. __

Qualification Status:

This package is being qualified through series of tests detailed in Qualification Test Plan #163305. The report for this QTP can be found in the attachment to this PCN.

Sample Status:

Qualification samples are not built ahead of time for all part numbers affected by this change. Please review the attached 'Affected Parts List' file for a list of affected part numbers with their associated ChipMOS Technologies Inc. sample ordering part numbers. Sample requests for products with "Subject to lead time" are not built ahead of time, they will be built to order and subject to standard lead times. Please contact your sales representative as soon as possible, but within 30 days of the date of this PCN, to place any sample orders.

Approximate Implementation Date:

Effective 90 days from the date of this notification, all shipments of the affected part numbers listed above will be assembled at ChipMOS Technologies Inc. or other approved assembly sites.

Anticipated Impact:

None anticipated. Customers may receive parts from ChipMOS Technologies Inc. or other approved assembly sites.

Method of Identification:

Cypress maintains traceability of product to the wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:

No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration